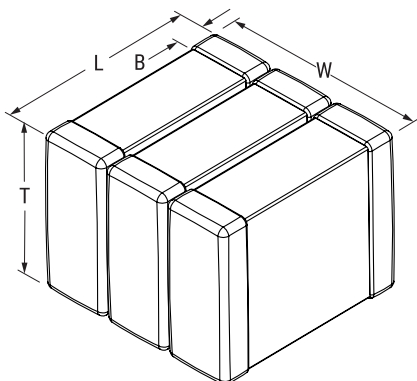


KONNEKT KC-Link, Ceramic, 0.66 uF, 10%, 500 VDC, COG, 3-Chip Low Loss Orientation.


Dimensions

L	9.3mm +/-0.6mm
W	7.7mm +/-0.6mm
T	10.2mm +/-0.4mm
B	1.27mm +/-0.4mm

Packaging Specifications

Weight:	3.3 g
Packaging:	T&R, 330mm
Packaging Quantity:	275

General Information

Series:	KONNEKT KC-Link
Style:	KONNEKT
Description:	KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I
Features:	Ultra-Stable
RoHS:	Yes
Termination:	Tin
AEC-Q200:	No
Notes:	3-Chip Low Loss Orientation.
Chip Size:	3640
MSL:	1

Specifications

Capacitance:	0.66 uF
Measurement Condition:	1 kHz 1.0Vrms
Capacitance Tolerance:	10%
Voltage DC:	500 VDC
Dielectric Withstanding Voltage:	750 VDC
Temperature Range:	-55/+150°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor:	0.1% 1 kHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	1.515 GOhms